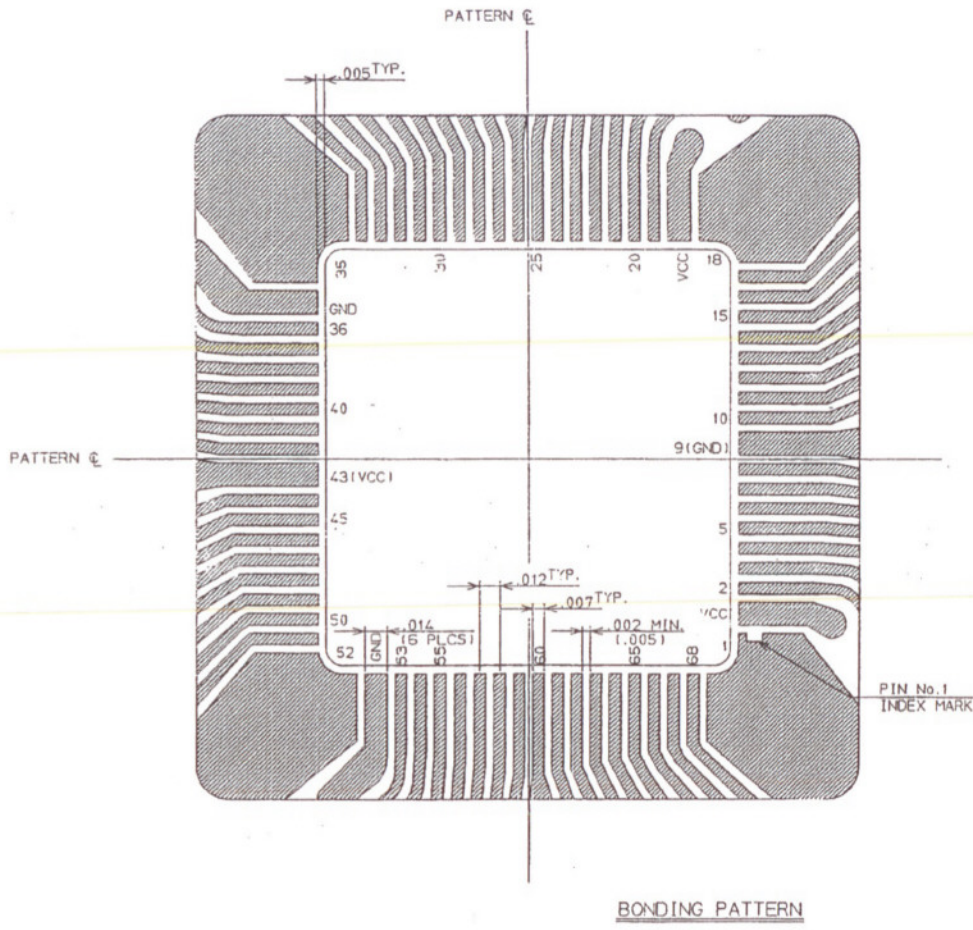


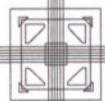
SSM P/N CPG06868



MODIFICATION					NAME 68 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN S.K	CHECKED K.K	APPROVED M.K	DATE MAY. 18 '89
					SCALE 20/1	MATERIAL	±			
							THIRD ANGLE PROJECTION			
	CHANGED				DATE	DRAWN	CHECKED	APPROVED	DRAWING NO. KD-P89362	SHEET 2/6



KYOCERA CORPORATION
KYOTO JAPAN


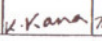




SPECTRUM
SEMICONDUCTOR MATERIALS, INC.

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WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.
1	B2	21	L3	41	G10	61	A6
2	B1	22	K4	42	G11	62	B5
3	C2	23	L4	43	F10	63	A5
4	C1	24	K5	44	F11	64	B4
5	D2	25	L5	45	E10	65	A4
6	D1	26	K6	46	E11	66	B3
7	E2	27	L6	47	D10	67	A3
8	E1	28	K7	48	D11	68	A2
9	F2	29	L7	49	C10		
10	F1	30	K8	50	C11		
11	G2	31	L8	51	B11	S/R	NC
12	G1	32	K9	52	B10	D/A	NC
13	H2	33	L9	53	A10		
14	H1	34	L10	54	B9		
15	J2	35	K10	55	A9	GND	F2 (9)
16	J1	36	K11	56	B8	VCC	F10 (43)
17	K1	37	J10	57	A8		
18	K2	38	J11	58	B7		
19	L2	39	H10	59	A7		
20	K3	40	H11	60	B6		

MODIFICATION						NAME 68 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
						SCALE \times	MATERIAL	S.K	K.K	M.K	MAY.18.'89
							\pm — THIRD ANGLE PROJECTION	  			
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	 KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-P89362			SHEET 3/6	

